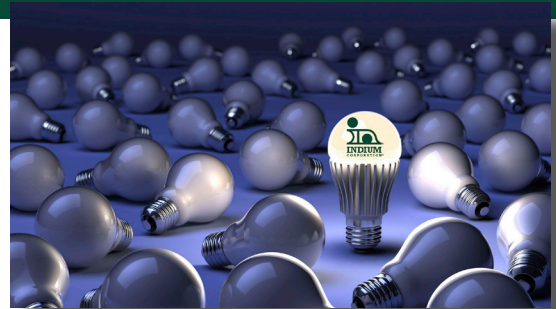


# Solder Materials and Compounds for LEDs

Indium Corporation provides a myriad of materials for Light Emitting Diode (LED) manufacturing. From gallium trichloride for MOCVD precursors to thermal interface materials, no other materials company provides so many solutions in so many layers of the ever-advancing LED.



## Compounds

We provide indium trichloride and gallium trichloride for manufacturing common MOCVD precursor materials (TMI and TMG, respectively) for LEDs.

Indium Corporation specializes in supplying In and Ga compounds at high purity, in large volume, and around the globe.



## Surface Mount Assembly and Solder Fortification

Indium solder pastes for LED deliver ultra-low voiding and clear residues.

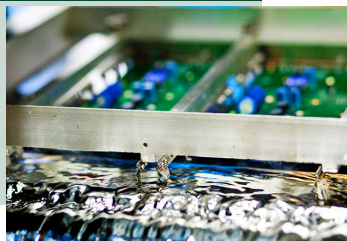
- L-220 for Pb-free (SAC305) applications
- L-180 for Sn63 applications

Indium Corporation also provides solder preform chips in tape & reel right off the shelf to help with solder starvation. It is easy to add bulk solder with preforms. We also provide solder preform washers and flux-coated preforms for soldering connectors to packages.



## Wave Soldering Materials and Rework

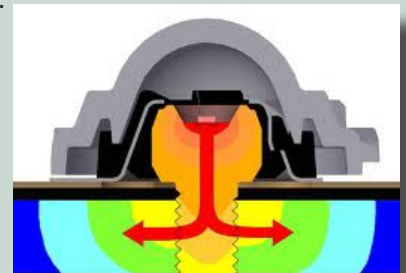
- Sn995 and Sn63 Bar Solder
- WF-9940 and WF-7745 (VOC Free) Wave Flux
- CW-207 Cored Wire—Pb and Pb-free flux-cored rework wire; clear residue; RA type flux.



## Thermal Interface

Indium Corporation is the world's largest supplier of metal TIMs. We offer a wide selection of metal-based TIMs for reflow or compression. Our patented Heat-Spring® compressible interface material at 86W/mK conductivity can solve many thermal interface issues.

The standard pack for Heat-Springs® is tape & reel and it is designed for both automated or hand assembly applications.

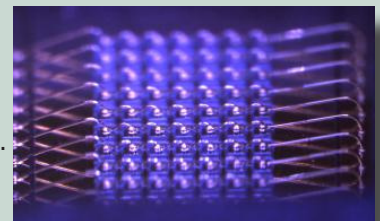


Our TIMs are used like a standard thermal pad. They have no residue and zero outgassing properties. Heat-Springs® are provided in custom or standard off-the-shelf shapes.

## Die-Attach and Fluxes

For LED companies needing high temperature die-attach materials, Indium Corporation is a global provider of solder paste, wire, and high purity AuSn preforms for fluxless die-attach.

For companies in need of materials for bumping wafers or soldering pre-plated dies for flip-chip, Indium Corporation provides "semiconductor grade" solder pastes and fluxes.



From One Engineer to Another®

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